

IN THE CLAIMS:

Please amend the claims as follows:

Claim 1 (Currently Amended): An embedding resin for embedding an electronic part in an insulating substrate, ~~assumes~~ **assuming** a color having a base color tone selected from among black, blue, green, red, orange, yellow, and violet, **and comprising a thermosetting resin and at least one inorganic filler,**

wherein the at least one inorganic filler has a particle size range of about 0.1 μm to 50 μm .

Claim 2 (Cancelled).

Claim 3 (Currently Amended): The embedding resin according to claim ~~[[2]]~~ **1**, wherein the thermosetting resin is at least one species selected from among a bisphenol-type epoxy resin, a naphthalene-type epoxy resin, a phenol-novolak-type epoxy resin, and a cresol-novolak-type epoxy resin.

Claim 4 (Original): The embedding resin according to claim 3, further comprising at least one coloring agent selected from among carbon black, a phthalocyanine-based pigment, an azo pigment, a quinoline-based pigment, an anthraquinone-based pigment, a triphenylmethane-based pigment, and an inorganic oxide.

Claim 5 (Cancelled).

Claim 6 (Original): The embedding resin according to claim 1, further comprising at least one coloring agent selected from among carbon black, a phthalocyanine-based pigment, an azo pigment, a quinoline-based pigment, an anthraquinone-based pigment, a triphenylmethane-based pigment, and an inorganic oxide.

Claim 7 (New): The embedding resin according to claim 1, wherein the thermosetting resin contains a photosensitive resin.

Claim 8 (New): The embedding resin according to claim 1, wherein the at least one inorganic filler is selected from among crystalline silica, fused silica, alumina, and silicon nitride.

Claim 9 (New): The embedding resin according to claim 1, wherein the at least one inorganic filler is subjected to surface treatment by use of a coupling agent.

Claim 10 (New): The embedding resin according to claim 4 wherein the amount of the coloring agent is 0.1-30 mass %.

Claim 11 (New): The embedding resin according to claim 6 wherein the amount of the coloring agent is 0.1-30 mass %.

Claim 12 (New): An embedding resin for embedding an electronic part in an insulating substrate comprising carbon black in an amount of 0.1-1.4 mass %.

Claim 13 (New): The embedding resin according to claim 12, furthering comprising a thermosetting resin and at least one inorganic filler.

Claim 14 (New): The embedding resin according to claim 13, wherein the thermosetting resin is at least one species selected from among a bisphenol-type epoxy resin, a naphthalene-type epoxy resin, a phenol-novolak-type epoxy resin, and a cresol-novolak-type epoxy resin.

Claim 15 (New): The embedding resin according to claim 13, wherein the at least one inorganic filler has a particle size range of about 0.1 μm to 50 μm .

Claim 16 (New): The embedding resin according to claim 13, wherein the thermosetting resin contains a photosensitive resin.

Claim 17 (New): The embedding resin according to claim 13, wherein the at least one inorganic filler is selected from among crystalline silica, fused silica, alumina, and silicon nitride.

Claim 18 (New): The embedding resin according to claim 13, wherein the at least one inorganic filler is subjected to surface treatment by use of a coupling agent.